

Abstract

Method for hermetic encapsulation of a component

5 For hermetic encapsulation of a component applied on a substrate (25) in a flip-chip construction, said component comprising a chip (1) with component structures (5), it is proposed to apply a material (35) onto the lower edge of the chip and regions of the substrate abutting the chip, and to apply thereon a first continuous metal layer (40) on the back side of the chip and on the material (35), as well as on  
10 edge regions of the substrate abutting the material. For hermetic encapsulation, a second sealing metal layer (45) is subsequently applied (by means of a solvent-free process) at least on those regions of the first metal layer (40) that cover the material (35).

15 Fig. 4B.